STN7120DN

N Channel Enhancement Mode MOSFET

50A

DESCRIPTION

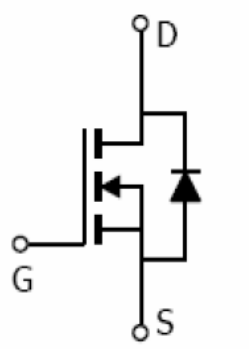
STN7120DN uses Trench MOSFET technology that is uniquely optimized to provide the most efficient nigh frequency switching performance. It has been optimized for low gate charge, low $R_{DS(ON)}$ and fast switching speed.

PIN CONFIGURATION
POWER PACK 5x6

Y : Year Code
A : Date Code
B : Package Code
C : Process Code

FEATURE

- 60V/10A, $R_{DS(ON)}$ = 12mΩ @V_{GS} = 10V
  60V/8A, $R_{DS(ON)}$ = 15mΩ @V_{GS} = 4.5V
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- PPAK5x6 package design



ABSOULTE MAXIMUM RATINGS (Ta = 25℃ Unless otherwise noted)

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.

STN7120DN

N Channel Enhancement Mode MOSFET

50A

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		VDSS	60	V
Gate-Source Voltage		VGSS	±20	V
Continuous Drain Current (TJ=150℃)	TA=25℃ TA=100℃	ID	50 31	A
Pulsed Drain Current		IDM	200	A
Continuous Source Current (Diode Conduction)		IS	35	A
Power Dissipation	TA=25℃	PD	96	W
Operation Junction Temperature		TJ	150	℃
Storage Temperature Range		TSTG	-55/150	℃
Thermal Resistance-Junction to Ambient		RθJA	62	℃/W

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.

ELECTRICAL CHARACTERISTICS (Ta = 25℃ Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,ID=250uA	60			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},ID=250uA	1.0		2.5	V
Gate Leakage Current	I_{GSS}	V_{DS}=0V,V_{GS}=±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V			1	uA
		V_{DS}=48V,V_{GS}=0V T_J=125℃			10	
Drain-source On-Resistance	$R_{DS(on)}$	V_{GS}=10V,I_D=10A V_{GS}=4.5V,I_D=8A		10 12	12 15	mΩ
Forward Transconductance	gfs	V_{DS}=10V,I_D=6A		11.7		S
Diode Forward Voltage	V_{SD}	I_S=1.0A,V_{GS}=0V			1.0	V
Dynamic						
Total Gate Charge	Q_g	V_{DS}=30V,V_{GS}=10V I_D≡10A		39.4	59	nC
Gate-Source Charge	Q_{gs}			5.9	9	
Gate-Drain Charge	Q_{gd}			8.8	14	
Input Capacitance	C_{iss}	V_{DS} =25V,V_{GS}=0V F=1MHz		2100	3050	pF
Output Capacitance	C_{oss}			165	240	
Reverse TransferCapacitance	C_{rss}			80	120	
Turn-On Time	$t_{d(on)}$	V_{DS}=15V,I_D=1A V_{GS}=10V, R_G=6Ω		9.8	18	nS
	tr			28.2	54	
Turn-Off Time	$t_{d(off)}$			45.3	86	
	tf			10.9	21	

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.

TYPICAL CHARACTERICTICS

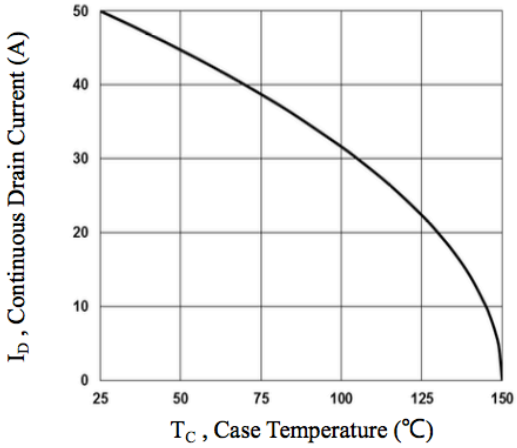


Fig.1 Continuous Drain Current vs. T_C

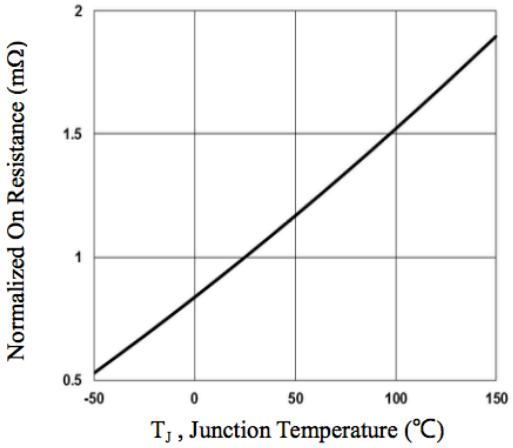


Fig.2 Normalized RDSON vs. T_J

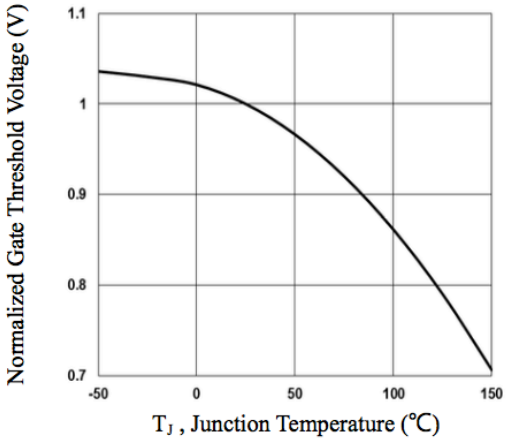


Fig.3 Normalized V_{th} vs. T_J

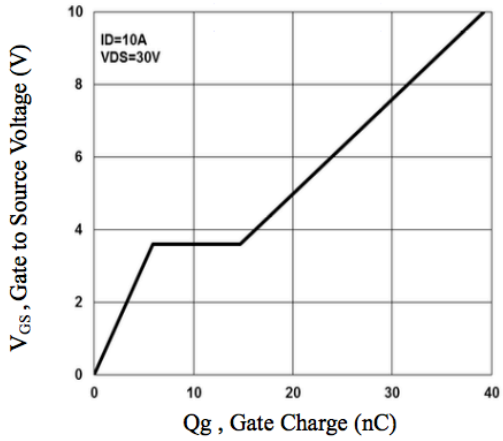


Fig.4 Gate Charge Waveform

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.

TYPICAL CHARACTERICTICS

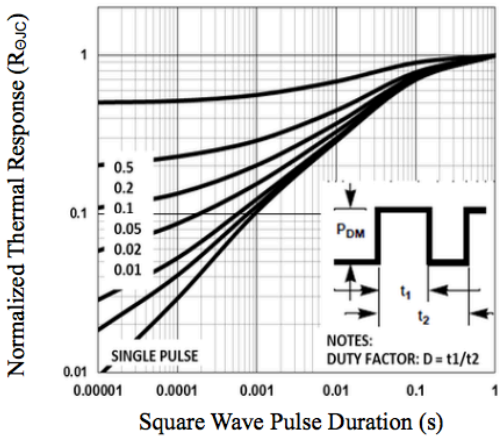


Fig.5 Normalized Transient Response

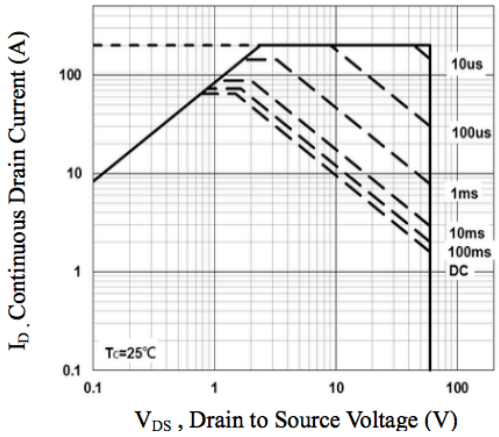


Fig.6 Maximum Safe Operation Area

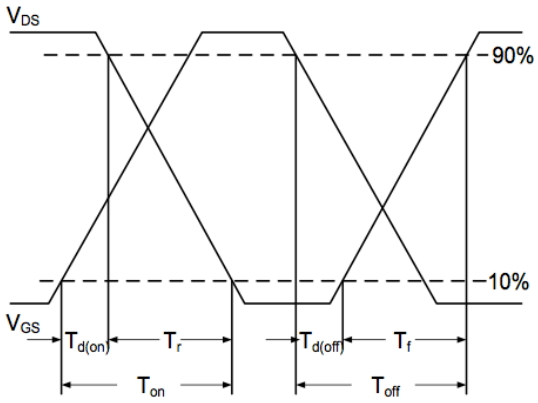


Fig.7 Switching Time Waveform

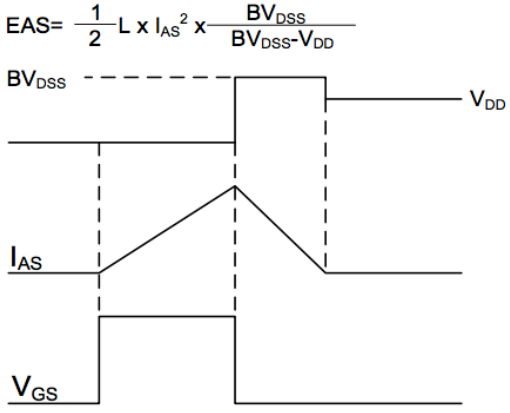
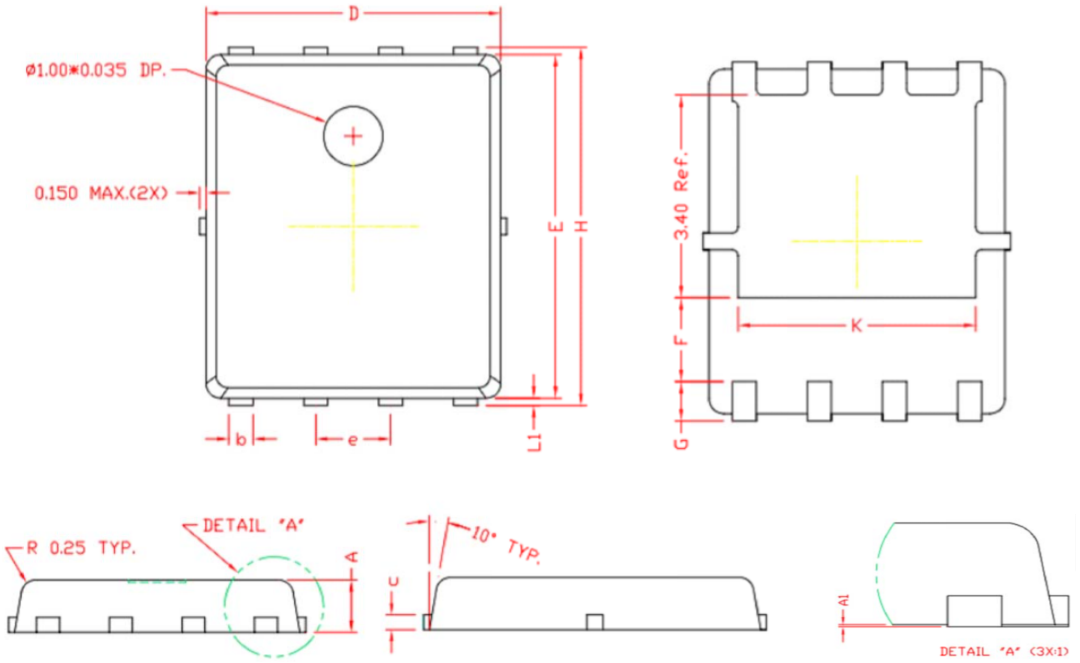


Fig.8 EAS Waveform

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.

POWER PACKAGE 5x6 OUTLINE



(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c		0.254 REF.	
D	4.90	5.00	5.10
F		1.40 REF.	
E	5.70	5.80	5.90
e		1.27 BSC.	
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G		0.60 REF.	
K		4.00 REF.	

STANSON TECHNOLOGY
120 Bentley Square, Mountain View, Ca 94040 USA
www.stansontech.com

Copyright © 2009, Stanson Corp.